



Product Change Notification

Change Notification #: 115189 - 00
Change Title: Select Intel® Edison Compute Module, Intel® Edison Kit for Arduino* and Intel® Edison Breakout Board Kit Products, PCN 115189-00, Label, Label Update
Date of Publication: December 16, 2016

Key Characteristics of the Change:
Label

Forecasted Key Milestones:

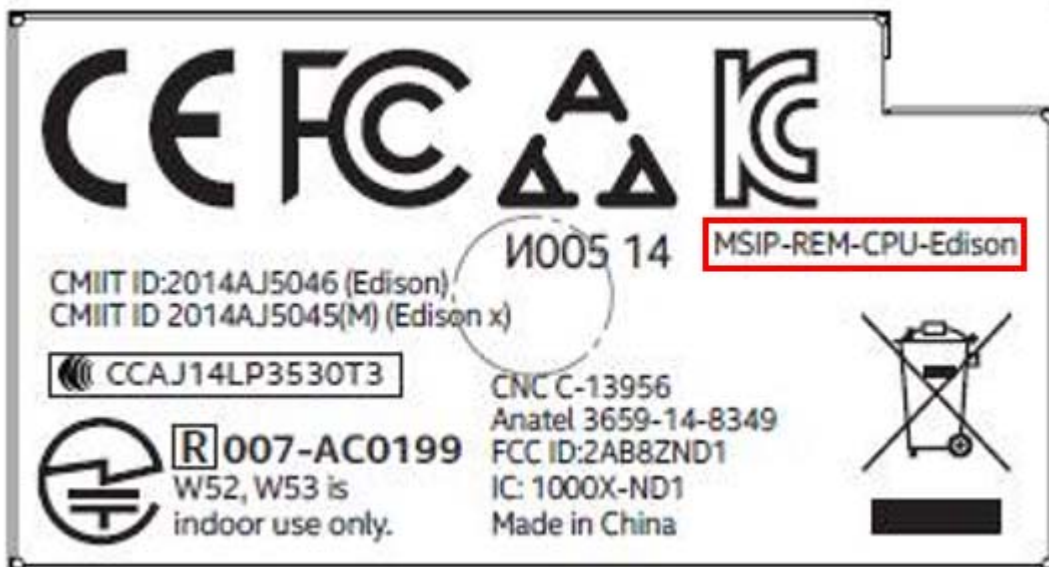
Date Customer Must be Ready to Receive Post-Conversion Material:	January 2, 2017
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Description of Change to the Customer:

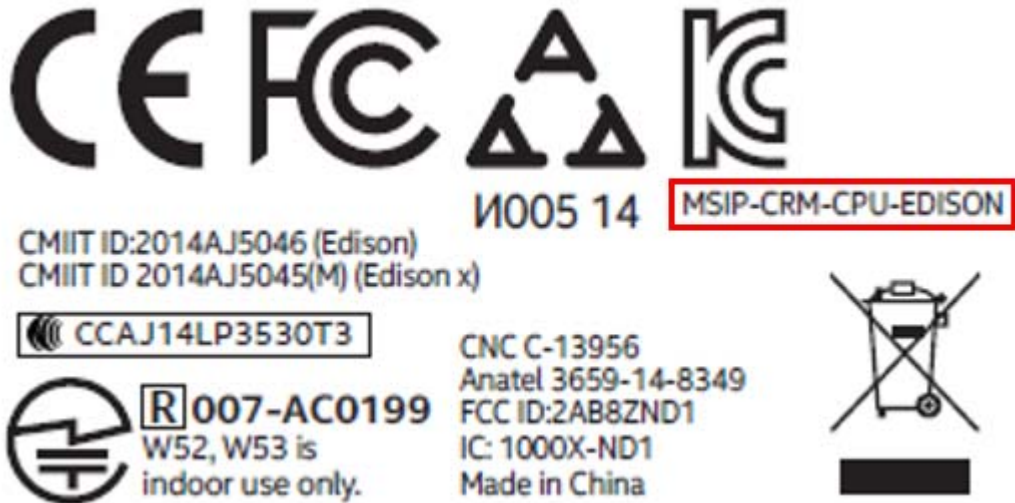
The Korea MSIP ID on the Edison pad printed label has changed from 'MSIP-REM-CPU-Edison' to 'MSIP-CRM-CPU-Edison'.

See image below for changes described:

Current label:



New label:



Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Customer can expect to receive mixed inventory until current inventory levels are depleted.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Edison Compute Module (IoT, On-Board Antenna) Single	EDI2.SPON.AL.S	939910
Intel® Edison Compute Module (IoT, Off-Board Antenna) Single	EDI2.SPOF.AL.S	939957
Intel® Edison Compute Module (IoT Wearable, On-Board Antenna) Single	EDI2.LPON.AL.S	939962
Intel® Edison Compute Module (IoT Wearable, Off-Board Antenna) Single	EDI2.LPOF.AL.S	939975
Intel® Edison Kit for Arduino*, Single	EDI2ARDUIN.AL.K	939976
Intel® Edison Breakout Board Kit, Single	EDI2BB.AL.K	939977
Intel® Edison Compute Module (IoT, On-Board Antenna) Single	EDI3.SPON.AL.S	939993
Intel® Edison Kit for Arduino*, Single	EDI3ARDUIN.AL.K	939997
Intel® Edison Breakout Board Kit, Single	EDI3BB.AL.K	939998

*Other names and brands may be claimed as the property of others.

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
December 16, 2016	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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